

Drawing Type	BILL OF MATERIALS
Drawing Title	EVM,TI Designs -1MSPS, 18-Bit, 35mW
Drawing Number	6572622
Revision	TIPD113-B
Data Class	TI INTERNAL DATA
Engineer	R Ordonez
Released By	B McKay
Release date	06/12/2013

NOTE: ASTERISK(*) NEXT TO PART MANUFACTURER'S NAME DENOTES POSSIBLE LONG LEAD TIME ITEM.

ITEM	QTY	MFG	MFG PART#	REF DES	DESCRIPTION	VALUE or FUNCTION
		TBD by TI (TURNKEY)				
	REF	TBD by TI	6572622TIPD113-B	-	ASSEMBLY	-
	REF	-	6572622TIPD113-B	-	SCHEMATIC	-
	1	TBD by TI	6572622TIPD113-B	-	FABRICATION	-
	REF	-	6572622TIPD113-B	-	ARTWORK	-
1	2	Emerson Network Power	142-0701-201	J4, J5	Connector, TH, SMA	
2	1	Samtec, Inc.	SSW-105-22-F-D-VS-K	J3-B	Connector, Header, 10-Pos (10x2), Receptacle, 100x100-mil Pitch	
3	2	Samtec, Inc.	TSM-110-01-T-DV-P	J1-T, J2-T	Header, 100mil, 10x2, SMD	
4	2	Samtec, Inc.	SSW-110-22-F-D-VS-K	J1-B, J2-B	Connector, Receptacle, 100mil, 10x2, Gold plated, SMD	
5	1	Samtec, Inc.	TSM-105-01-T-DV-P	J3-T	Header, 100mil, 5x2, SMD	
6	2	MuRata	GRM31CR71C106KAC7L	C17, C19	CAP, CERM, 10uF, 16V, +/-10%, X7R, 1206	
7	2	Sullins Connector Solutions	PBC03SAAN	JP1, JP2	Header, TH, 100mil, 1x3, Gold plated, 230 mil above insulator	
8	2	MuRata	GRM21BR71A106KE51L	C6, C22	CAP, CERM, 10uF, 10V, +/-10%, X7R, 0805	
9	3	Kemet	C0603C102J5GAC	C16, C18, C20	CAP, CERM, 1000pF, 50V, +/-5%, C0G/NP0, 0603	
10	1	Keystone	5000	TP1	Test Point, Miniature, Red, TH	
11	9	MuRata	GRM188R71A105KA61D	C4, C7, C8, C9, C12, C13, C15, C21, C24	CAP, CERM, 1uF, 10V, +/-10%, X7R, 0603	
12	2	Panasonic	ERJ-3RQFR22V	R11, R16	RES, 0.22 ohm, 1%, 0.1W, 0603	
13	1	TDK	C1608COG1H22J	C3	CAP, CERM, 2200pF, 50V, +/-5%, C0G/NP0, 0603	
14	3	3M	969102-0000-DA	SH-JP1, SH-JP2, SH-JP3	Shunt, 100mil, Gold plated, Black	
15	1	Vishay-Dale	CRCW060310R0FKEA	R22	RES, 10.0 ohm, 1%, 0.1W, 0603	
16	3	Vishay-Dale	CRCW06031K00FKEA	R12, R13, R37	RES, 1.00k ohm, 1%, 0.1W, 0603	
17	5	Vishay-Dale	CRCW060320K0FKEA	R17, R18, R19, R27, R31	RES, 20.0k ohm, 1%, 0.1W, 0603	
18	4	AVX	06033C104KAT2A	C2, C5, C10, C23	CAP, CERM, 0.1uF, 25V, +/-10%, X7R, 0603	
19	2	Yageo America	RC0603FR-0722RL	R9, R10	RES, 22.0 ohm, 1%, 0.1W, 0603	
20	6	Panasonic	ERJ-3GEY0R00V	R3, R5, R6, R23, R25, R30	RES, 0 ohm, 5%, 0.1W, 0603	
21	7	Yageo America	RC0603FR-0747RL	R1, R2, R28, R29, R32, R33, R35	RES, 47.0 ohm, 1%, 0.1W, 0603	
22	1	Microchip	24LC256-I/ST	U7		
23	1	Texas Instruments	ADS8881IDGS	U1	ADC 1MSPS 18bit Fully-Diff MSOP-10	
24	1	TE Connectivity	5-146261-1	JP3	Header, 100mil, 2x1, Gold plated, TH	
25	1	Texas Instruments	THS4281DGK	U2	IC OpAmp GP R-R 90MHz SGL MSOP-8	
26	2	Texas Instruments	OPA333AIDBVT	U3, U5	OpAmp, Low Power, Low Drift, 1.8V	
27	1	Texas Instruments	OPA2320AIDGKR	U6	OpAmp, RRIO, 0.9pA IB, 20MHz	
28	8		N/A	C1, C11, C14, C25, C26, R24, R26, R34	Uninstalled	
29	1	Texas Instruments	REF5045AIDGKT	U4	VREF PREC 4.5V MSOP-8	

SPECIAL NOTES AND INSTRUCTIONS						
Alternate Reference Circuit						
1	0	MuRata	GRM185R61A105KE36D	C1	CAP, CERM, 1 uF, 10V, +/- 10%, X5R, 0603	
2	0	MuRata	GRM188R60J476ME15D	C2	CAP, CERM, 47 uF, 6.3 V, +/- 20%, X5R, 0603	
3	0	MuRata	GRM21BR61E106KA73L	C3	CAP, CERM, 10 uF, 25 V, +/- 10%, X5R, 0805	
4	0	Panasonic	ERJ3LWFR005V	R1	RES, 0.005, 1%, 0.25 W, AEC-Q200 Grade, 0603	
5	0	Panasonic	ERJ-3RQFR22V	R2	RES, 0.22, 1%, 0.1 W, 0603	
6	0	Texas Instruments	REF6045IDGKR	U1B	High Precision Voltage Reference	

END OF BOM

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